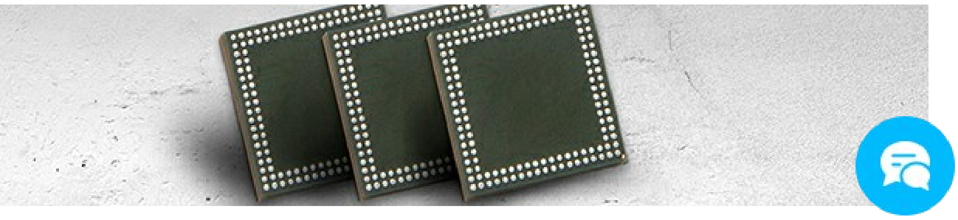
ePoP Component - Embedded package on package memory for device manufacturers



Kingston ePoP is a highly integrated JEDEC standard component that combines eMMC and LPDRAM into one package with a tiny footprint. ePoP is mounted directly on top of a compatible host CPU, which effectively saves board space and ensures optimum performance as a result of the memory's proximity to the host CPU. It is an ideal solution for highly space-constrained systems such as wearables.

Request Information

ePoP Part Numbers and Specifications

P/N	Capacity	Speed Mode	e•MMC version	Package Size
04EPOP04-NL3DM627	4GB MLC + 4Gb LPDDR3	HS400	5.0	10 x 10 x 1.0 (136 Ball)
04EPOP08-NL3DM627	4GB MLC + 8Gb LPDDR3	HS400	5.0	10 x 10 x 1.0 (136 Ball)
08EPOP04-NL3DT227	8GB TLC + 4Gb LPDDR3	HS400	5.0	10 x 10 x 1.0 (136 Ball)
08EPOP08-NL3DT227	8GB TLC + 8Gb LPDDR3	HS400	5.0	10 x 10 x 1.0 (136 Ball)

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